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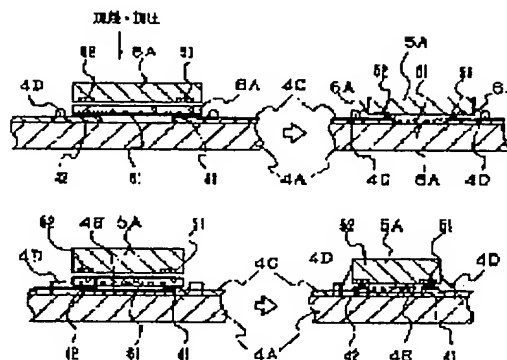
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(54) WIRING BOARD

(57)Abstract:

PROBLEM TO BE SOLVED: To improve adhesion by forming a land having a height not less than that of a wiring pattern at a slightly wide area from a mounting region to block adhesives from extruding at the time of compression bonding of a chip.

SOLUTION: A land 4D forming a part of the wiring pattern on a board 4A is formed in an area, slightly larger than the projection area of a chip on the board 4A. When the chip 5A is compressively bonded through an anisotropically conductive adhesive 6A on a wiring pattern 4C, the adhesive 6A extrudes from the periphery of the mounting area due to the heat and pressure applied to the chip 5A, but is blocked by the land 4D having a thickness not less than that of wiring patterns 4a, 42 on the board 4A, resulting in the deposit of the adhesive to the outer wall of the chip 5A. This increases the adhesion area of the anisotropically conductive adhesive 6A and improves the adhesion.



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